

## ABSTRACT

2 A multi-chip stack flip-chip package comprises a substrate and a chip assembly on  
3 the substrate. The chip assembly includes a dummy chip and a flip chip. The dummy  
4 chip has a redistribution layer that has a plurality of bump pads for mounting the flip chip,  
5 a plurality of peripheral pads for electrically connecting to the substrate, and a plurality of  
6 integrated circuit traces connecting the bump pads with the peripheral pads. The  
7 dummy chip is disposed between the flip chip and the substrate as an electrically  
8 connecting interface between the flip chip and the substrate for multi-chip flip-chip stack  
9 and fine pitch flip-chip mounting.

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